Manufacturer:
ÅngströmBond®

Product Name:
ÅngströmBond® AB9001MTUP Thixotropic Clear Epoxy, Room Temperature & Heat Cure (2.5g)

Manufacturer Part Number:
AB9001MTUP-2.5G

ÅngströmBond® Adhesives

Advanced Polymers for High Tech Applications

ÅngströmBond® 9001 MT

Thixotropic Adhesive for MT, MTRJ and Specialty Connectors

Description:

ÅngströmBond® **9001 MT** is a two-part, room temperature curing adhesive designed specifically for use in MT and MTRJ connector assemblies. The blue color of this non-sagging thixotropic adhesive allows for easy polishing. It produces low stress during cure, thereby eliminating fiber cracking in both single and multimode connectors. ÅngströmBond® **9001 MT** is an excellent choice sealing and encapsulating small units where a strong bond to glass, ceramic, plastics or metals are required. It offers high impact, moisture, and chemical resistance. Available in unpigmented version: AB9001MTUP.

Typical Physical Properties:

AB9001MT Color Mixed:	Dark blue
AB9001MTUP Color Mixed:	Clear
Specific Gravity, g/cc:	1.15
Mixed Viscosity @ 25°C, cps:	50,000-55,000
Service Temperature Range, °C:	-65 to 130
Glass Transition, °C: (cured 90C/15 min)	93
Hardness, Shore D:	78
Mix Ratio by Weight, Resin to Hardener:	100/30
Dielectric Strength:	> 400
Solids Content:	100%
Lap Shear Strength, psi:	2950

Handling Characteristics:

Working Life:	30-45 Minutes
Minimum Cure Schedule:	
@25°C	18 Hours
@65°C	1 Hour
@90°C	15 Minutes

Other intermediate cure schedules are possible depending upon user's application.

Application Directions:

Bi-pack Packages: Safely remove the divider clip from the package. Knead the package (multiple passes over the edge of a table works well) until a uniform color is achieved and the material is thoroughly mixed. Ensure all material from the corners of the bi-pack are mixed in. 25 passes over the edge of a table are recommended. Cut open end of package to dispense.

De-airing:

De-airing of mixing epoxy should be done to remove any entrapped air. Vacuum de-airing should be performed.

Handling:

To ensure better performance of the potted or encapsulated components, adequate cleaning of components should be performed to remove contamination such as dust, moisture, salt and oils that can cause poor adhesion.

Storage:

Two component epoxy resin systems should be stored between 65°F and 90°F. Refrigeration is not recommended. Most two-component epoxy resin systems are naturally susceptible to crystallization, especially when stored at temperatures below the recommended storage temperatures. Do not store epoxy materials near sources of heat. All materials should be kept in the original packaging to prevent foreign matter contamination and moisture entry.